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Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

# **EF Series Power MOSFET With Fast Body Diode**



PRODUCT SUMMARY

V<sub>DS</sub> (V) at T<sub>J</sub> max.

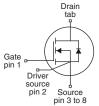
Q<sub>q</sub> max. (nC)

Configuration

Q<sub>gs</sub> (nC)

Q<sub>qd</sub> (nC)

R<sub>DS(on)</sub> typ. (Ω) at 25 °C



N-Channel MOSFET

0.090

650

51

16

8

Single

 $V_{GS} = 10 \overline{V}$ 

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### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

- Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
- High-intensity discharge (HID)
- Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SIHK105N60EF-T1GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			$V_{DS}$	600	V		
Gate-source voltage			$V_{GS}$	± 30	V		
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	24	A		
	VGS at 10 V	T <sub>C</sub> = 100 °C		15			
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	61			
Linear derating factor				1.14	W/°C		
Single pulse avalanche energy b			E <sub>AS</sub>	154	mJ		
Maximum power dissipation			$P_{D}$	142	W		
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-source voltage slope		T <sub>J</sub> = 125 °C	dv/dt	100	V/ns		
Reverse diode dv/dt <sup>c</sup>		uv/at	50	V/IIS			

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 3.3 A
- c.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	=	50 <sup>c</sup>	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.88	C/VV		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	600	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.56	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		3.0	-	5.0	V
	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zeve gete veltege dvein euwent		V <sub>DS</sub> =	480 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	2	mA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.090	0.105	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 10 V, I <sub>D</sub> = 12 A	-	2.1	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	2301	-	pF
Output capacitance	C <sub>oss</sub>		V <sub>DS</sub> = 100 V,		81	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 200 kHz		-	1	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		-	85	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	462	-	
Total gate charge	Qg				34	51	
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> = 10 V I <sub>D</sub> = 12 A, V <sub>DS</sub> = 480 V		-	16	-	nC
Gate-drain charge	$Q_{gd}$		!		8	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 15 A,		-	31	62	- ns
Rise time	t <sub>r</sub>			-	51	77	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		40	80	
Fall time	t <sub>f</sub>	1		-	30	60	
Gate input resistance	$R_g$	f = 1 MHz		0.4	0.8	1.6	Ω
<b>Drain-Source Body Diode Characteristic</b>	es						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	24	
Pulsed diode forward current	I <sub>SM</sub>			-	-	61	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 12 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	102	292	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 12 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 400 \text{ V}$		-	0.6	1.2	μC
Reverse recovery current	I <sub>RRM</sub>			_	13	-	Α

#### Notes

- d.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V
- e.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V
- f. When mounted on 1" x 1" FR4 board



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

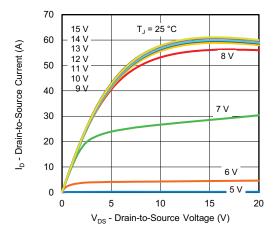


Fig. 1 - Typical Output Characteristics

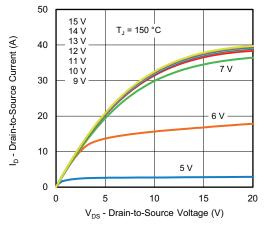


Fig. 2 - Typical Output Characteristics

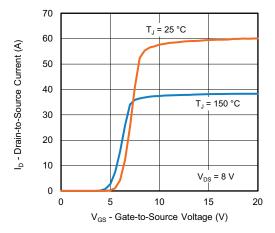


Fig. 3 - Typical Transfer Characteristics

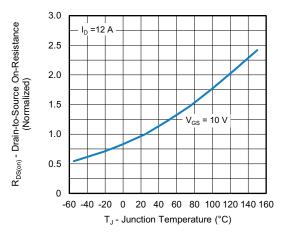


Fig. 4 - Normalized On-Resistance vs. Temperature

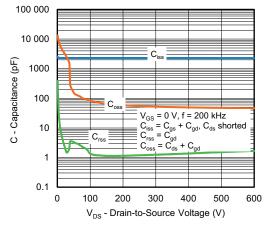


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

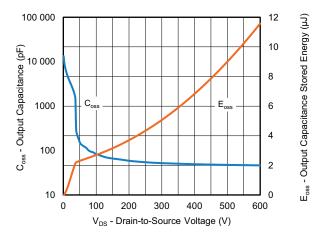


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



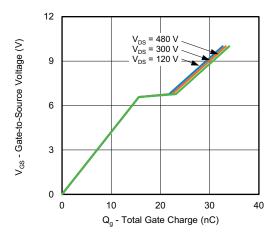


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

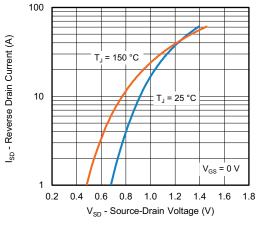


Fig. 8 - Typical Source-Drain Diode Forward Voltage

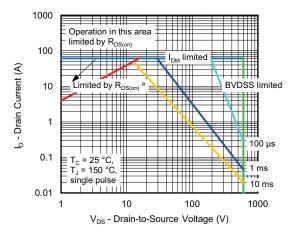


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS} > minimum \ V_{GS}$  at which  $R_{DS(on)}$  is specified

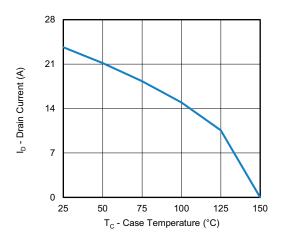


Fig. 10 - Maximum Drain Current vs. Case Temperature

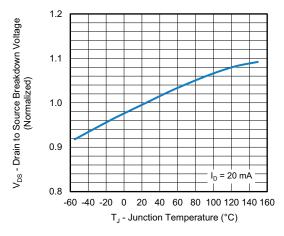


Fig. 11 - Temperature vs. Drain-to-Source Voltage



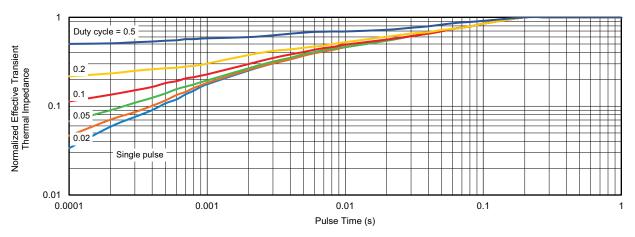


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

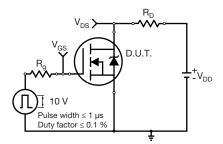


Fig. 13 - Switching Time Test Circuit

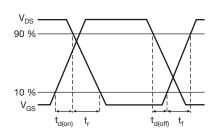


Fig. 14 - Switching Time Waveforms

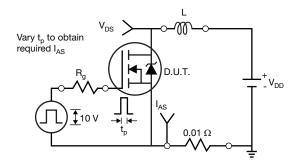


Fig. 15 - Unclamped Inductive Test Circuit

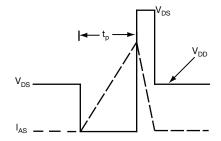


Fig. 16 - Unclamped Inductive Waveforms

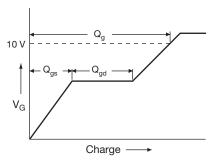


Fig. 17 - Basic Gate Charge Waveform

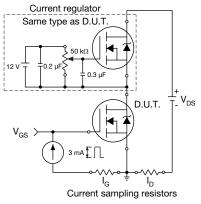
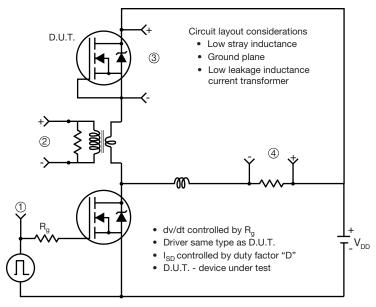


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



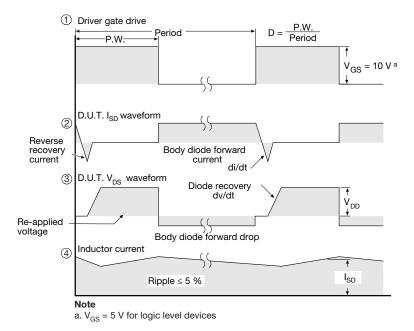
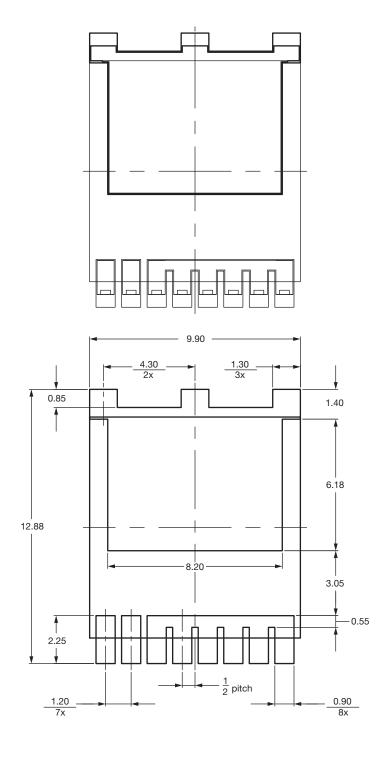


Fig. 19 - For N-Channel

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# Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



#### Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



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